



4N60

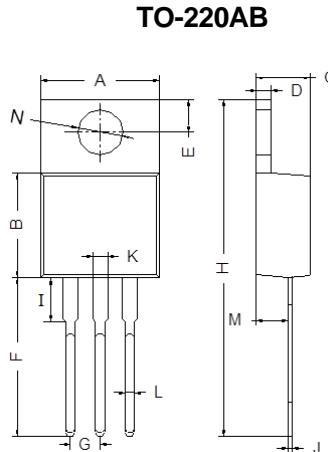
4A N-Channel Power MOSFET

Features

New technology for high voltage device
 Low on-resistance and low conduction losses
 Small package
 Ultra Low Gate Charge cause lower driving requirements
 100% Avalanche Tested
 ROHS compliant

Mechanical Data

Case : TO-220AB
Terminals : Solder plated, solderable per MIL-STD-750,
 Method 2026
Polarity : As marked
Mounting Position : Any

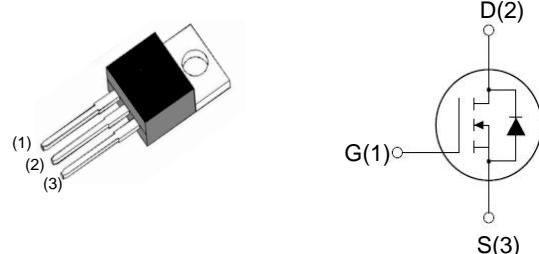


TO-220AB		
Dim	Min	Max
A	9.80	10.30
B	8.30	8.90
C	4.37	4.77
D	1.10	1.45
E	2.62	2.87
F	13.14	13.74
G	2.41	2.67
H	28.40	29.16
I	3.55	4.05
J	0.35	0.58
K	1.20	1.32
L	0.68	0.94
M	2.40	2.60
N	3.71	3.91

All Dimensions in mm

Application

Power factor correction (PFC)
 Switched mode power supplies(SMPS)
 Uninterruptible Power Supply (UPS)



Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz,resistive or inductive load, for capacitive load current derate by 20%.

Table 1. Absolute Maximum Ratings ($T_c=25^\circ\text{C}$)

Parameter	Symbol	4N60	Unit
Drain-Source Voltage ($V_{GS}=0\text{V}$)	V_{DS}	600	V
Gate-Source Voltage ($V_{DS}=0\text{V}$),AC (f>1 Hz)	V_{GS}	± 30	V
Continuous Drain Current at $T_c=25^\circ\text{C}$	$I_D(\text{DC})$	4	A
Continuous Drain Current at $T_c=100^\circ\text{C}$	$I_D(\text{DC})$	2.5	A
Pulsed drain current (Note 1)	$I_{DM(\text{pulse})}$	16	A
Maximum Power Dissipation($T_c=25^\circ\text{C}$) Derate above 25°C	P_D	165.56 1.32	W W/ $^\circ\text{C}$
Single pulse avalanche energy (Note2)	E_{AS}	610.9	mJ
Avalanche current (Note 1)	I_{AR}	4.0	A
Repetitive Avalanche energy , t_{AR} limited by $T_{j\max}$ (Note 1)	E_{AR}	15.0	mJ



Parameter	Symbol	4N60		Unit
Drain Source voltage slope, $V_{DS} \leq 480$ V,	dV/dt	50		V/ns
Reverse diode dV/dt , $V_{DS} \leq 480$ V, $I_{SD} < I_D$	dV/dt	15		V/ns
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55...+150		°C

* limited by maximum junction temperature

Table 2. Thermal Characteristic

Parameter	Symbol	4N60		Unit
Thermal Resistance, Junction-to-Case (Maximum)	R_{thJC}	0.755		°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R_{thJA}	80.25		°C /W

Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	600			V
Zero Gate Voltage Drain Current($T_c=25^\circ C$)	I_{DSS}	$V_{DS}=600V, V_{GS}=0V$			10	μA
Zero Gate Voltage Drain Current($T_c=125^\circ C$)	I_{DSS}	$V_{DS}=480V, V_{GS}=0V$			100	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2		4	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=2A$		1700	2400	$m\Omega$
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=50V, V_{GS}=0V, F=1.0MHz$		702		pF
Output Capacitance	C_{oss}			89		pF
Reverse Transfer Capacitance	C_{rss}			2.69		pF
Total Gate Charge	Q_g	$V_{DS}=480V, I_D=4A, V_{GS}=10V$		13.3	28	nC
Gate-Source Charge	Q_{gs}			3.6		nC
Gate-Drain Charge	Q_{gd}			4.9		nC
Switching times						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=380V, I_D=2.5A, R_G=5\Omega, V_{GS}=10V$		8		nS
Turn-on Rise Time	t_r			4		nS
Turn-Off Delay Time	$t_{d(off)}$			52	70	nS
Turn-Off Fall Time	t_f			9	18	nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I_{SD}	$T_c=25^\circ C$			4	A
Pulsed Source-drain current(Body Diode)	I_{SDM}				16	A
Forward On Voltage	V_{SD}	$T_j=25^\circ C, I_{SD}=4A, V_{GS}=0V$		0.9	1.2	V
Reverse Recovery Time	t_{rr}	$T_j=25^\circ C, I_F=2A, di/dt=100A/\mu s$		200		nS
Reverse Recovery Charge	Q_{rr}			0.6		uC
Peak reverse recovery current	I_{rrm}			6		A

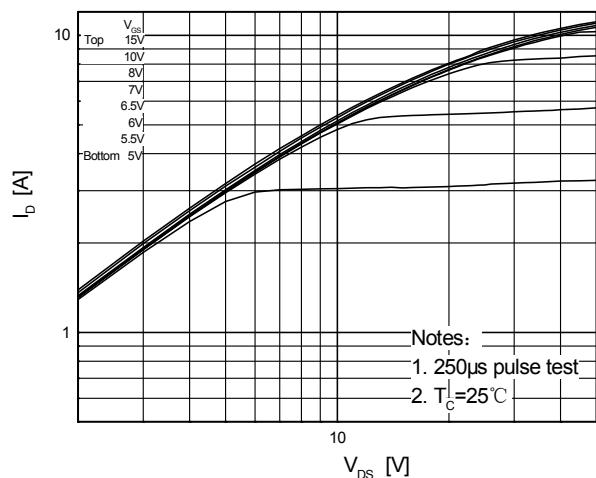
Notes: 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2. $T_j=25^\circ C, V_{DD}=50V, V_G=10V, R_G=25\Omega$

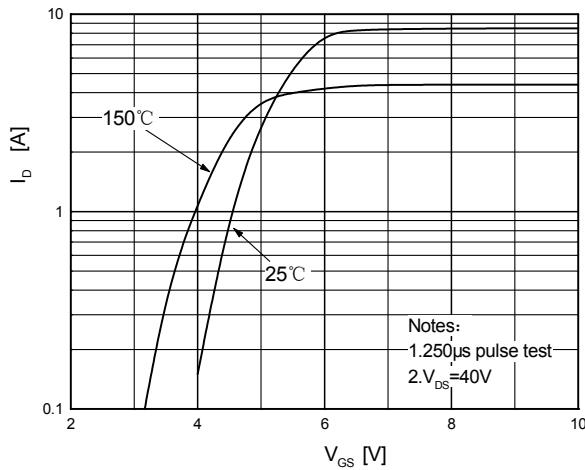


ELECTRICAL CHARACTERISTICS (curves) 4N60

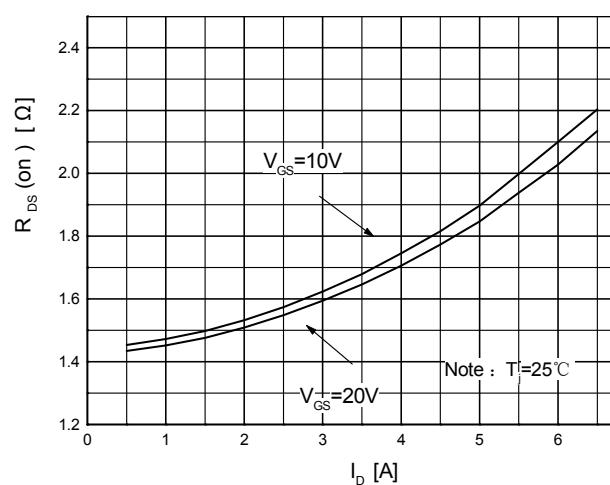
On-Region Characteristics



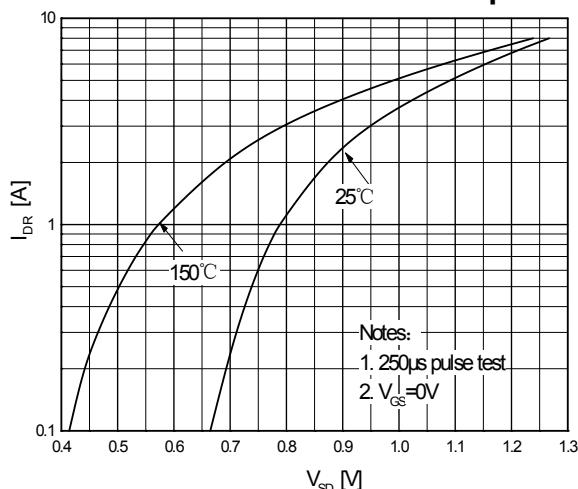
Transfer Characteristics



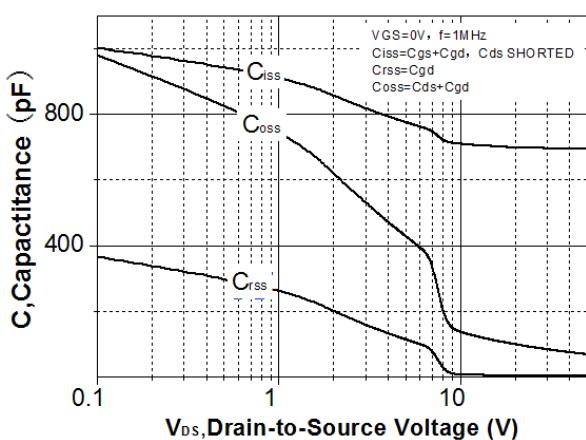
On-Resistance Variation vs. Drain Current and Gate Voltage



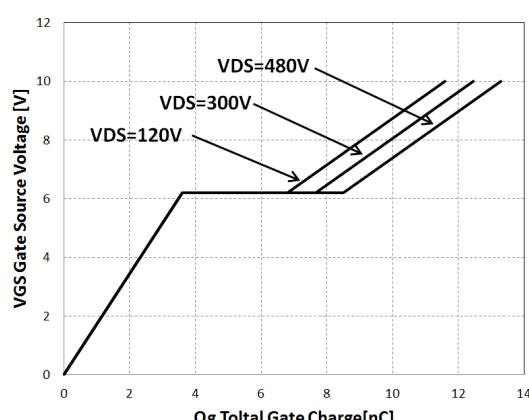
Body Diode Forward Voltage Variation vs. Source Current and Temperature



Capacitance Characteristics



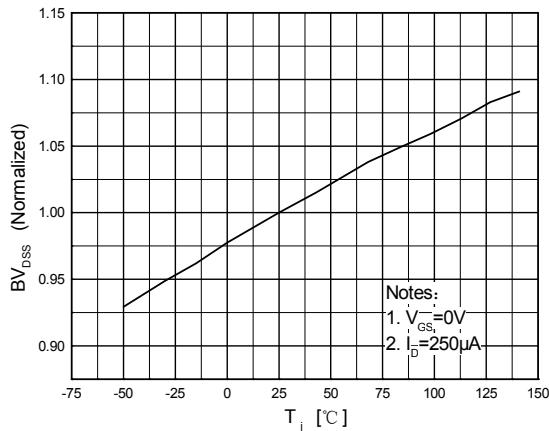
Gate Charge Characteristics



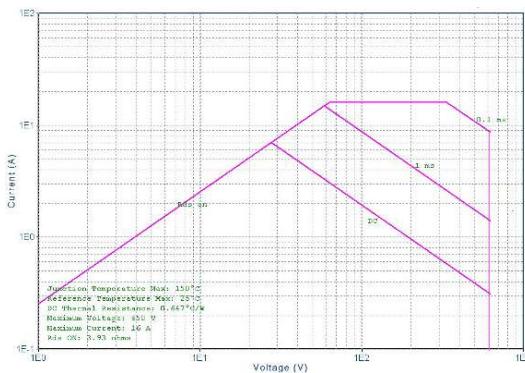


ELECTRICAL CHARACTERISTICS (curves)

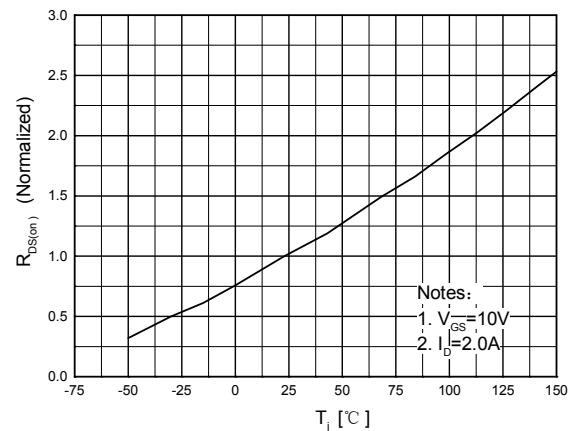
**Breakdown Voltage Variation
vs. Temperature**



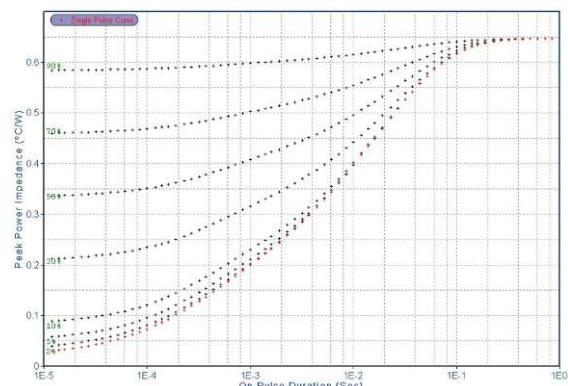
**Maximum Safe Operating Area
For 4N60**



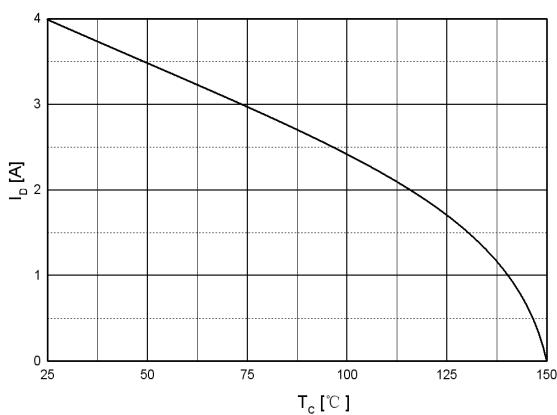
**On-Resistance Variation
vs. Temperature**



**Transient Thermal Response Curve
For 4N60**



**Maximum Drain Current
vs. Case Temperature**



单击下面可查看定价，库存，交付和生命周期等信息

[>>ZG\(中鑫半导体\)](#)